Table 2 SCREENING REQUIREMENTS FOR PEMS 1/ (Page 1 of 3)

Screen	Test Method and Conditions	Level 1	Level 2	Level 3
1. External visual, and serialization 2/	Per paragraph 5.3.1. of PEM-INST-001	X	X	X
2. Temperature cycling	MIL-STD-883, Method 1010, Condition B (or to the manufacturer's maximum storage temperature range, whichever is less). Temperature cycles, minimum.	20	20	10
3. Radiography 3/	Per paragraph 5.3.2. of PEM-INST-001	X	X	X
4. C-SAM inspection 4/	Per paragraph 5.3.3. of PEM-INST-001	X	X	X
5. Initial (pre-burn-in) electrical measurements (EM) 5/	Per device specification, at 25 °C At min. and max. rated operational temperatures.	X X	X X	X -
6. Engineering review (Steps 1 to 5) 6/				
7. Static (steady-state) burn-in (BI) test at 125 °C or at max. operating temperature 7/	MIL-STD-883, Method 1015, condition A or B. Hours, minimum depending on the BI temperature.	240 hrs. at 125 °C 445 hrs. at 105 °C 885 hrs. at 85 °C 1,560 hrs. at 70 °C	160 hrs. at 125 °C 300 hrs. at 105 °C 590 hrs. at 85 °C 1,040 hrs. at 70 °C	160 hrs. at 125 °C 300 hrs. at 105 °C 590 hrs. at 85 °C 1,040 hrs. at 70 °C
7a. Post static BI electrical measurements @ 25 °C	Per device specification. Calculate Delta when applicable.	X	X	X
9. Dynamic burn-in test at 125 °C or at max. operating temperature 7/	MIL-STD-883, Method 1015, Cond. D. Hours, minimum.	Same as test step 7.	Same as test step 7.	Same as test step 7.
10. Final parametric and functional tests	Per device specification (at 25 °C, maximum, and minimum rated operating temperatures).	X	X	X
11.Calculate percent defective (Steps 7 to 10) 6/	Maximum acceptable PDA.	5%	10%	10%
12. External visual/packing 2/	Per paragraph 5.3.1 and Section 8 of PEM-INST-001.	X	X	X

Notes on next page.